

# NCE20N50,NCE20N50F

**Pb-Free Product** 

# **Super Junction MOSFET**

NCE N-Channel Enhancement Mode Power MOSFET

### **General Description**

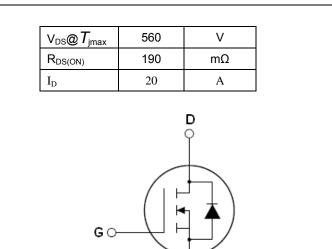
The series of devices use advanced super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

#### Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- ●small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested

# Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

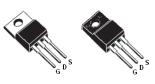


# Schematic diagram

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#### Package Marking And Ordering Information

Device	Device Package	Marking
NCE20N50	TO-220	NCE20N50
NCE20N50F	TO-220F	NGE20N30



TO-220 TO-220F

### Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃)

Parameter	Symbol	NCE20N50	NCE20N50F	Unit
Drain-Source Voltage (VGs=0V)	Vds	500		V
Gate-Source Voltage (VDs=0V)	Vgs	<u>±</u>	:30	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	20	20*	А
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	12.5	12.5*	А
Pulsed drain current (Note 1)	DM (pluse)	60	60*	А
Drain Source voltage slope, VDS = 480 V, ID = 20 A, Tj = $125 \ ^{\circ}\text{C}$	dv/dt	50		V/ns
Maximum Power Dissipation(Tc=25°C)	PD	208	34.5	W
Derate above 25°C		1.67	0.28	W/°C
Single pulse avalanche energy (Note 2)	Eas	6	90	mJ
Avalanche current <sup>(Note 1)</sup>	I <sub>AR</sub>	2	20	А



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Repetitive Avalanche energy , $t_{\text{AR}}$ limited by $T_{\text{jmax}}$ (Note 1)	E <sub>AR</sub>	1	mJ
Operating Junction and Storage Temperature Range	$T_J,T_STG$	-55+150	°C

\* limited by maximum junction temperature

#### Table 2. Thermal Characteristic

Parameter	Symbol	NCE20N50	NCE20N50F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	0.6	3.6	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	80	°C /W

## Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

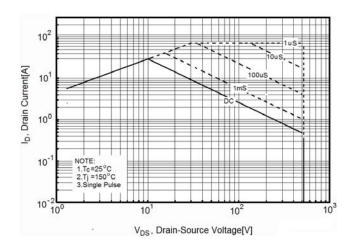
Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	500			V
Zero Gate Voltage Drain Current(Tc=25°C)	I <sub>DSS</sub>	V <sub>DS</sub> =500V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =500V,V <sub>GS</sub> =0V			100	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	2.5	3	3.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A			190	mΩ
Dynamic Characteristics						
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> = 20V, I <sub>D</sub> = 10A		17.5		S
Input Capacitance	Clss			2300		PF
Output Capacitance	Coss	V <sub>DS</sub> =100V,V <sub>GS</sub> =0V, F=1.0MHz		95		PF
Reverse Transfer Capacitance	Crss			7		PF
Total Gate Charge	Qg	)/ -290)// -204		88		nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =380V,I <sub>D</sub> =20A, V <sub>GS</sub> =10V		10		nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> -10V		50		nC
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>			10		nS
Turn-on Rise Time	tr	V <sub>DD</sub> =380V,I <sub>D</sub> =20A,		5		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> =3.6Ω,V <sub>GS</sub> =10V		67	100	nS
Turn-Off Fall Time	t <sub>f</sub>			4	12	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T -25°0			20	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			60	А
Forward on voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =20A,V <sub>GS</sub> =0V		0.9	1.3	V
Reverse Recovery Time	t <sub>rr</sub>	T: 05%0   000  :/// 4000/		500		nS
Reverse Recovery Charge	Q <sub>rr</sub>	− Tj=25°C,I <sub>F</sub> =20A,di/dt=100A/μs		11		nC

Notes 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R<sub>G</sub>=25 $\Omega$ 



# **TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)**



# Figure1. Safe operating area for NCE20N50

#### Figure3. Source-Drain Diode Forward Voltage

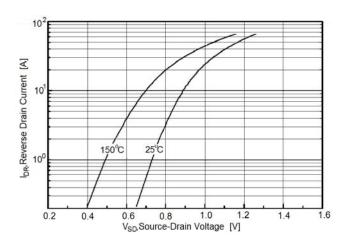
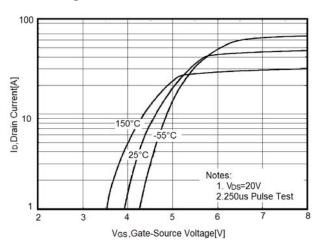
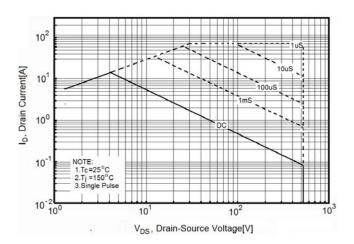


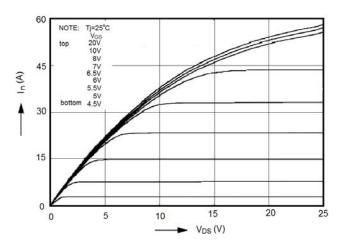
Figure 5. Transfer characteristics



#### Figure2. Safe operating area for NCE20N50F



#### Figure4. Output characteristics



#### Figure6. Static drain-source on resistance

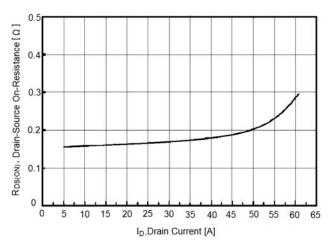




Figure7. R<sub>DS(ON)</sub> vs Junction Temperature

Figure8. BV<sub>DSS</sub> vs Junction Temperature

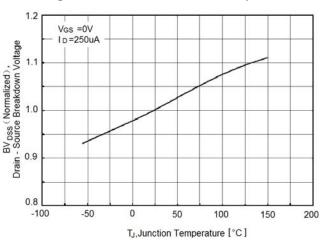


Figure9. Maximum I<sub>D</sub> vs Junction Temperature

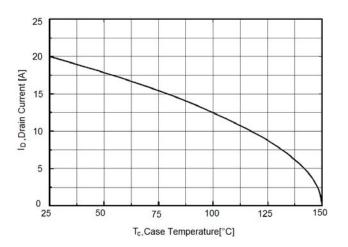


Figure10. Capacitance

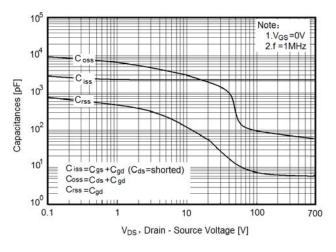


Figure10. Gate charge waveforms

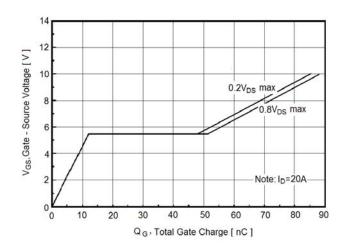
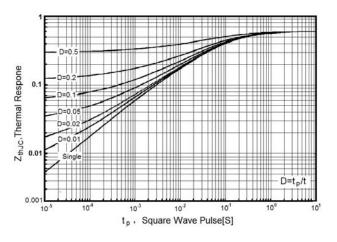
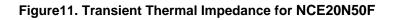


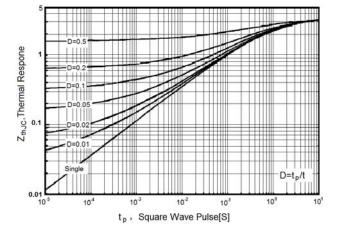
Figure11. Transient Thermal Impedance for NCE20N50



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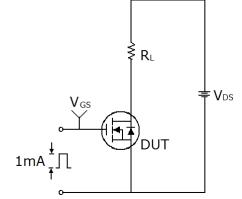




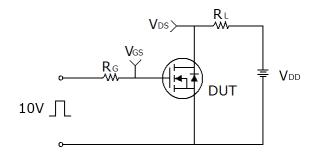


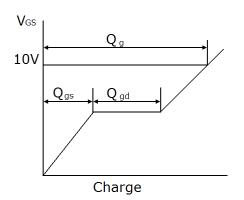
# Test circuit

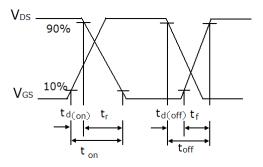
1) Gate charge test circuit & Waveform



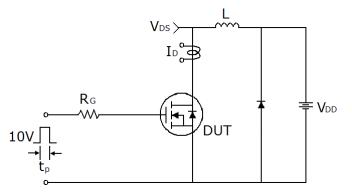
2) Switch Time Test Circuit:

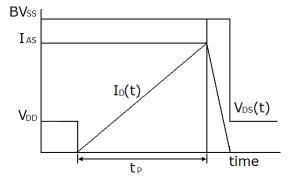






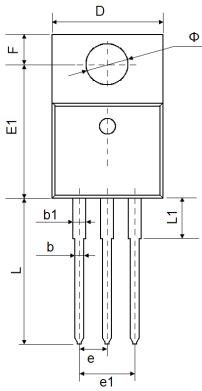
3) Unclamped Inductive Switching Test Circuit & Waveforms

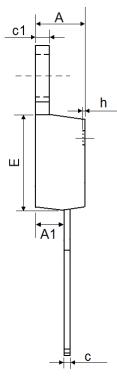


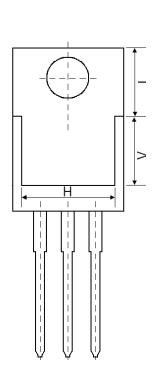




# **TO-220-3L Package Information**



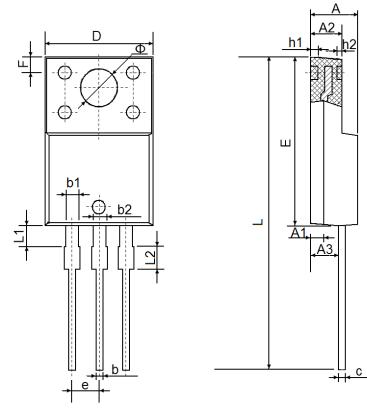




Symbol	Dimension	s In Millimeters	Dimensions In Inches	
	Min.	Max.	Min.	Max.
А	4.470	4.670	0.176	0.184
A1	2.520	2.820	0.099	0.111
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	10.010	10.350	0.394	0.407
E	8.500	8.900	0.335	0.350
E1	12.060	12.460	0.475	0.491
е	2.54	40 TYP.	0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.590	2.890	0.102	0.114
Н	8.44	10 REF.	0.332 REF.	
h	0.000	0.300	0.000	0.012
L	13.400	13.800	0.528	0.543
L1	3.560	3.960	0.140	0.156
V	6.060 REF.		0.239	REF.
I	6.60	6.600 REF.		) REF.
Φ	3.735	3.935	0.147	0.155



# **TO-220F Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
А	4.300	4.700	0.169	0.185		
A1	1.30	OREF	0.051REF			
A2	2.800	3.200	0.110	0.126		
A3	2.500	2.900	0.098	0.114		
b	0.500	0.750	0.020	0.030		
b1	1.100	1.350	0.043	0.053		
b2	1.500	1.750	0.059	0.069		
С	0.500	0.750	0.020	0.030		
D	9.960	10.360	0.392	0.408		
E	14.800	15.200	0.583	0.598		
е	2.54	0TYP. 0.100TYP		2.540TYP.		)TYP
F	2.70	2.700REF		0.106REF		
Φ	3.50	3.500REF		BREF		
h1	0.800REF		0.031REF			
h2	0.500REF		0.020REF			
L	28.000	28.400	1.102	1.118		
L1	1.700	1.900	0.067	0.075		
L2	1.900	2.100	0.075	0.083		



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